Non-RoHS Compliant Diode Part Number End of Life

Bourns has successfully provided RoHS compliant diodes with part number suffix “LF” to our customers since January 2005, with the result that the majority of Bourns customers have already switched to RoHS compliant part numbers during the past 3 years.

Due to lack of orders for SnPb models over the past 12 months with customers preferring to use RoHS compliant parts instead, effective immediately Bourns will no longer accept orders for diode part numbers using SnPb termination plating (without “LF” suffix).

The affected Bourns® part numbers include the following part number series:

- CD214A-B Series
- CD214C-B Series
- CD214A-T Series
- CD214C-T Series
- CD214B-B Series
- CD216A-B Series
- CD214B-T Series
- CD1607-B Series

To avoid customer production down time, Bourns is strongly urging and requesting that customers using Bourns® diode part numbers (without suffix “LF”) switch to alternative lead free part numbers using the "LF" suffix with 100 % matte tin plating.

The RoHS compliant Bourns® diode part number with the "LF" suffix is backward compatible to the SnPb lower temperature 235 °C ~ 240 °C solder reflow process. I have attached solder bath temperature data to support the backward compatibility.
# Bourns Inc.

## HI-REL EXPERIMENT SUMMARY

**DEPARTMENT:** QA  
**PRODUCT:** SMD SnPb bath  
**CRITERIAL:**  
- \( V_f (V) < mV \) @IF= A  
- \( PIV(V) > v \) @IR= uA  
- \( IR(uA) < uA \) @PIV= V

<table>
<thead>
<tr>
<th>NO. TEST ITEMS</th>
<th>CONDITION</th>
<th>Machine No.</th>
<th>DURATION</th>
<th>FAILURE RATE</th>
<th>PARAMETER</th>
<th>X BAR</th>
<th>S DEV.</th>
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<td>Q0136</td>
<td>5 SECS</td>
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**COMMENTS:**

**TESTED BY:** Zhang-xiaomei

**ENGINEER:**

**MANAGER:**
PART NO: SMA

TEST ITEM: Solderability

TEST CONDITION: 225 +/- 5°C

DURATION: 5 SECS

FAILURE RATE: 0/10

TESTED BY: Zhang-xiaomei

ENGINEER:

DATE: AUG/17/2006

EXP.#: N/A

LOT NO: N/A

D/C: N/A

P/N: N/A

FIV-QA409-0
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FAILURE RATE: 0/10

TESTED BY: Zhang-xiaomei

ENGINEER:  

FIV-QA409-0
PART NO: SMB

TEST ITEM: Solderability

TEST CONDITION: 225 +/- 5°C

DURATION: 5 SECS

DATE: AUG/17/2006

EXP.#: N/A

LOT NO: N/A

D/C: N/A

P/N: N/A

FAILURE RATE: 0/10

TESTED BY: Zhang-xiaomei

ENGINEER:
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FAILURE RATE: 0/10

TESTED BY: Zhang-xiaomei

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TESTED BY: Zhang-xiaomei

ENGINEER:
PART NO: SMC
TEST ITEM: Solderability
TEST CONDITION: 240 +/- 5°C
DURATION: 5 SECS

DATE: AUG/17/2006
EXP.#: N/A
LOT NO: N/A
D/C: N/A
P/N: N/A

FAILURE RATE: 0/10
TESTED BY: Zhang-xiaomei
ENGINEER:

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